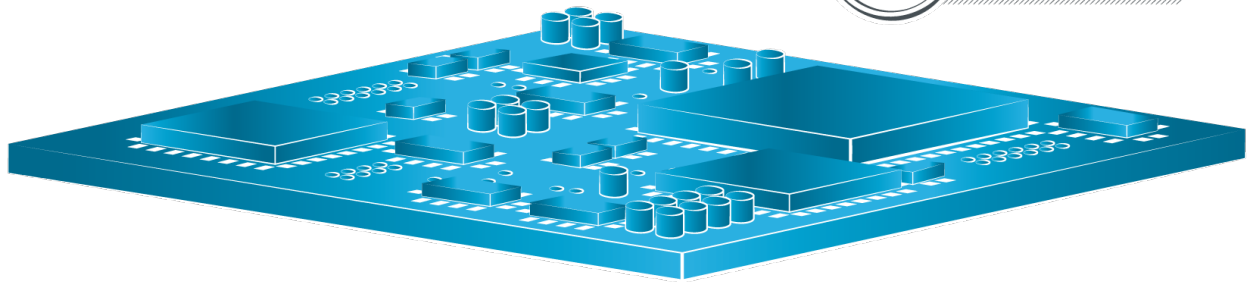
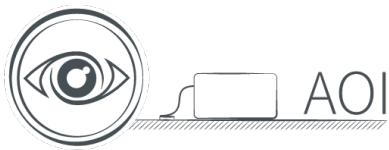
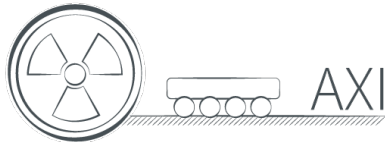




Technology range

Overview · Inspection Solutions



AOI for SMD

- use as inline & stand-alone systems
- flexible configuration variants as 2D/3D AOI

AXI for SMD & THT

- 3D technology for inspection of double side assembled PCBs
- 2D technology for high-speed inspection of single side assembled PCBs
- high test coverage by combination of AXI and integrated AOI



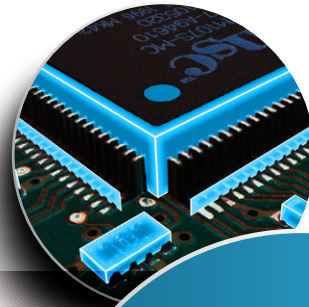
SPI for solder & sinter pastes

- high-precision shadow-free 3D measurement of solder and sinter pastes
- process optimization through closed loop to paste printers and connection of measurement data with AOI/AXI



AOI for THT

- PCB transport with and without carrier
- configuration variants for upper transport (component and solder joint inspection) and lower return (solder joint inspection)



3D measurement technologies

- 100% 3D measurement
- maximum fault detection based on 360° measurement and inspection
- shadow-free 3D measurement of connectors and press-fits

Selective solder joint inspection

- AOI module for integration into the periphery of selective soldering systems
- flexible configuration of the camera and lighting head
- modular communication interfaces



PILOT VERIFY PILOT STATISTIC



PILOT CONNECT PILOT SUPERVISOR



PILOT AOI·AXI·SPI PILOT INSPECT

Inspection software

- exceptionally easy operation and maximum inspection reliability
- extensive component library with individually expandable entries and test functions
- complete offline programming and optimization

Verification and statistics

- presentation of all detected faults with numerous additional illustrations for reliable verification
- comprehensive analysis to optimise production quality

Data management & central Multi-Line verification

- management of inspection data and system information
- combined display of inspection results and central verification over Ethernet
- flexible MES communication